PATENTS ONLY (ref OG 7/28/92)

05-28-2002



102103401

ks: __ereof.

Name of Party(ies) conveying an 1. interest:

> Hiroshi Inagawa Nobuo Machida Kentaro Oishi

To the Honorable Commis

Please record the attached

Name and Address of Party(ies) receiving an interest:

HITACHI, LTD. 6, Kanda Surugadai 4-chome Chiyoda-ku, Tokyo, JAPAN And

Hitachi ULSI Systems Co., Ltd. 22-1, Josuihoncho 5-chome, Kodaira-shi, Tokyo, Japan

3. Description of the interest conveyed:

<u>Assignment</u>

4. Application number(s) or patent number(s).

Additional sheet attached? ___ Yes XXX No

2.

If this document is being filed together with a new application, the execution date of the application is: DATE

A. Patent Application No.(s)

B. Patent No.(s)

09/695,036

5. Name and address of party to whom correspondence concerning document should be mailed:

> John R. Mattingly Mattingly, Stanger & Malur, P.C. 1800 Diagonal Road, Suite 370 Alexandria, Virginia 22314

- 6. Number of applications and patents involved: One
- 7. Amount of fee enclosed or authorized to be charged: \$40.00
- 8. The Commissioner is hereby authorized to charge Deposit Account No. 50-1417 if no check is attached.

DO NOT USE THIS SPACE

05/24/2002 LMUELLER 00000019 09695036

01 FC:581

40.00 DP

- Execution date of attached document: September 18, 2000
- 10. To the best of my knowledge and belief, I declare under penalty of perjury under the laws of the United States of America that the foregoing information is true and correct and that any attached copy is a true copy of the original document.

John R. Mattingly

Name of Person Signing

May 21, 2002

Date

Total number of pages being submitted: 1

PATENT REEL: 012918 FRAME: 0294

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD. and Hitachi ULSI Systems Co., Ltd., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, and 22-1, Josuihoncho 5-chome, Kodaira-shi, Tokyo, Japan, respectively, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD. and Hitachi ULSI Systems Co., Ltd., their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

invented by me— (if only one is named below) or us— (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner ship of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD, and Hitachi ULS1 Systems Co., Ltd., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD, and Hitachi ULSI Systems Co., Ltd.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

RECORDED: 05/21/2002

PATENT REEL: 012918 FRAME: 0295

Date Signed